
Okoljsko preskušanje - 2-83. del: Preskusi - Preskus Tf: preskus spajkanja elektronskih komponent za površinsko montažo (SMD) z metodo za ugotavljanje omočljivosti z uporabo spajkalne paste

Environmental testing - Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

Umweltprüfungen - Teil 2-83: Prüfungen - Prüfung Tf: Prüfung der Lötbarkeit von Bauelementen der Elektronik für Oberflächenmontage (SMD) mit der Benetzungswaage unter Verwendung von Lotpaste

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Essais d'environnement - Partie 2-83: Essais - Essai Tf: Essai de brasabilité des composants électroniques pour les composants pour montage en surface (CMS) par la méthode de la balance de mouillage utilisant de la pâte à braser

Ta slovenski standard je istoveten z: EN 60068-2-83:2011

ICS:

19.040	Preskušanje v zvezi z okoljem	Environmental testing
31.020	Elektronske komponente na splošno	Electronic components in general

SIST EN 60068-2-83:2012

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60068-2-83

October 2011

ICS 19.040; 31.190

English version

**Environmental testing -
Part 2-83: Tests -
Test Tf: Solderability testing of electronic components for surface
mounting devices (SMD) by the wetting balance method using solder
paste
(IEC 60068-2-83:2011)**

Essais d'environnement -
Partie 2-83: Essais -
Essais Tf: Essai de brasabilité des
composants électroniques pour les
composants pour montage en surface
(CMS) par la méthode de la balance de
mouillage utilisant de la pâte à braser
(CEI 60068-2-83:2011)

Umweltprüfungen -
Teil 2-83: Prüfungen -
Prüfung Tf: Prüfung der Lötbarkeit von
Bauelementen der Elektronik für
Oberflächenmontage (SMD) mit der
Benetzungswaage unter Verwendung von
Lotpaste
(IEC 60068-2-83:2011)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 91/975/FDIS, future edition 1 of IEC 60068-2-83, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-2-83:2011.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-07-12
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2014-10-12

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-69	NOTE Harmonized as EN 60068-2-69.
IEC 61189-5	NOTE Harmonized as EN 61189-5.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	-

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

Environmental testing – Part 2-83: Tests – Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

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Essais d'environnement – Partie 2-83: Essais – Essai Tf: Essai de brasabilité des composants électroniques pour les composants pour montage en surface (CMS) par la méthode de la balance de mouillage utilisant de la pâte à braser

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

**Part 2-83: Tests – Test Tf: Solderability testing
of electronic components for surface mounting devices (SMD)
by the wetting balance method using solder paste**

FOREWORD

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International Standard IEC 60068-2-83 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/975/FDIS	91/992/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents as indicated below.

IEC takes no position concerning the evidence, validity and scope of patent rights.

The holders of the patent rights have assured the IEC that they are willing to negotiate licences either free of charge or under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holders of these patent rights are registered with IEC. Information may be obtained as indicated below.

- a) EU patent 0920488.4 “Synchronous test method for assessing soldering pastes”¹
 Gen3 Systems LTD
 Unit B2
 Armstrong Mall
 Farnborough GU14 0NR
 United Kingdom
- b) JP Patent 2630712 “Testing method of characteristics of solder paste and the equipment for the test”
 Malcom Co., Ltd
 4-15-10 Honmachi, Shibuya-ku
 Tokyo, 151-0071
 Japan
- c) Patent JP 3789041 “Solderability measuring apparatus”
 Patent JP 3552061 “Solderability tester and solderability test method”
 Patent JP 3498100 “Method and device for testing solderability and microcrucible for testing”
 Patent JP 3153884 “Measuring device for soldering performance of cream solder”
 Tarutin Kester Co., Ltd.
 2-20-11 Yokokawa,
 Sumida-ku
 Tokyo, 130-0003
 Japan
- d) Sony Corporation
 1-7-1 Konan Minato-ku
 Tokyo 108-0075
 Japan

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¹ Status of patent: Pending.

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